



Hall Devices: Physic & Application to Field Measurements

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Scope (and limitations) of the course

Answers to the questions:

- Hall effect : what is it ? V
 B
- Hall devices: basic parameters, practical aspects, type of Hall probes
- Multi axis Hall sensors : status and future challenges
- Magnetic field measurements with Hall probes: advantages and limitations.
- Applications for field measurements in accelerator magnets: (examples of measurements at CERN and at the Paul Scherrer Institute)



* T. Friedman, "the World is flat" (2006)

Not in that course :

- The technology of fabrication like CMOS and (sub) micrometer Hall devices
- Magnetic measurements in inhomogeneous magnetic field
- Hall measurements in a fast AC magnetic field
- High frequency effects
- The Hall device as meansfor characterizing the semiconductors (see Popovic-2004)
- Hall effect in sensing applications (see Ramdsen-2006)





Outline

1. Hall sensors : Overview of the basic properties

- Hall effect : physical effect
- Some basic properties:
 - sensitivity &Offset
 - Noise, Temperature sensitivity, linearity
 - Calibration
 - Zoology of Hall probes

2. Three axis Hall magnetic devices.

- Three axis sensors
- The new generation : Magnetometers with IC Hall sensors
- Future challenges

Summary : Advantages and limitations in magnetic field measurements

3. Application in magnetic field measurements in beam line magnets

- Ex 1 : Measurements of conventional magnets at the Paul Scherrer Institute
- Ex 2: Sextupole measurements in CERN LHC dipoles
- Ex 3 : Field measurements in Insertion Devices

4. Summary



Hall effect : The physical principle





The Hall effect : physical principle



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The Hall effect : physical principle (2)



Choice of the material



Remarks

•InAs and InSb have a small gap and the sensitivity is strongly temperature dependent.

- •Si is interesting as it is compatible with integrated electronic technology.
- •The Hall effect is polarity dependent: R_H determines the sign of the charge carriers q.
- •If I or B change direction, the polarity of the Hall voltage flips.





Geometry consideration





"Planar" Hall effect (Goldberg&Davis 1954, B.Berkes 2001)



Additional transverse voltage : $U_{planar} \sim B_p^2 \sin 2\phi$

Additional term that are equiv. to an anisotropic change of the magneto resistance: $\Delta \rho_b \sim -P_H B_p^2$



U_{planar} is important when mapping 3-D fields

NB : can be eliminated by flipping the probe at 180°, inverting the field direction, turning the probe (Φ =0)

 $U_p=0$ for $\phi=0$ and $\phi=k \pi$





Hall sensors: Basic characteristics





Hall sensor description

Active part : semiconductor element (bulk or film) ("sensing material", 0.01..0.1 mm)
Four terminals: sensing and biasing contacts
Substrate (ceramic): support and thermal stability
Encapsulated or not.





From Ripka [5]

Active part (InAs film) and construction scheme



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Hall sensor Characteristics







Transfer function and sensitivity

Sensitivity S is defined as the change in output (V) for a given change in input (B). It expresses the response of the output voltage to a magnetic field.

- •Measured in units of output quantity per units of input quantity (V/T)
- •S depends on the operating conditions (T,B).
- •S not a constant in the all the domain of B-interest: calibration $V_H = F(B)$ needed

$$S = \frac{V}{B_{\perp}}$$
 in [V/T], B_{\perp} is the normal component to the Hall plate

Other figure of merits : The Current related sensitivity S_I

$$S_{I} = \frac{V}{B_{\perp}I_{bias}}$$
 in [V/AT], I_{bias} is the biasing current

Hall "plate like" sensors (range 0-5 T, 1.5K-300 K): S_{I} ~ 1-100 V/AT

Sensitivity is changing with time



periodic re-calibration V_H=F(B)





Hall probe calibration



•High Homog. field ($\sim 10^{-5}$) calibration magnet

- •NMR probes (reference for B reading)
- •Stable HP current source (0.01%)
- •DVM to read V_{H} (integ. time 20 ms)
- Hall probe perpendicular to B_{cal} (within 0.1°) and NMR at the center of the calibration magnet
 Temperature regulation



Hall probe -





To treat the non linearity : $B = c0 + c1 \cdot U + c2 \cdot U2 + ... cn \cdot Un$ (n=9 in that case)

More complex in the case of a 3D Hall sensor (planar effect)!







Offset

•Offset : Parasitic voltage that exists without magnetic field (B=0, $V_{output} \neq 0$) Offset V_{off} or equivalent magnetic induction B_{off} (typically 0.1-10 mT...)

Main Origins : Bellekom and Mounter, "Sensors and Materials",5 (1994)
Fabrication variables: Impurities, crystal defects, photo mask misalignment, misalignment to the crystal plane, misalignments in sense contacts.
Thermal effect :temperature gradients along the hall element.
Stress effect : Electrical resistance changes due to mechanical (piezo-restivity)

•Offset varies: in time, B, temperature (packaging stress effect), : T_{coeff} of offset.





Temperature and field dependence of the Sensitivity

Temperature dependence of S_I

•**T-dependence of the mobility:** $\mu = \mu_0 (\frac{T_0}{T})^{\alpha}, 2 \le \alpha \le 2.3$

•Intrinsic semiconductor

 $n_i \equiv n_0 \exp^{-E_g}$

Linearity error

•Deviation of the V_H=f (B) from the prescribed straight line

• NL often expressed in % (typically 0.01..0.1 %...)





Noise Voltage

It limits the detestability of the magnetic field and the stability of the output signal

Many sources of noise voltage occurred during a measurements with an Hall generator :

•Inherent Noise

 \checkmark Very low frequency noise V_{lf} due to T-variation of R_{in},

✓ Noise from the bias current and offset voltage drifts

 \checkmark The noise coming from the amplifiers.

✓ **Thermal noise** : Random motion of carriers: It varies with T and the bandwidth Δf of the detector. $< V_{th}^2 >= 4 \cdot k_B \cdot T \cdot R_{out} \cdot \Delta f$

 \checkmark 1/f noise due to the current flow through the generator (pronounced below 100 Hz)



Voltage noise spectral density

And also....

•Transmitted noise from external sources like:

✓ 50 Hz power

✓ the switching noise (spinning current technique)

Typical cures:

Filtering and bandwidth reduction , spinning current technique above f_{c}

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Types of Hall sensors (plate like)



LHP-NU LHP-NP

LHP-NA

VALUE

0 - 30

1.5 - 350

100

150

> 10

< 0.2

< 0.1

< 1

2.10-5

3.10⁻⁵

< 100

< 0.02

0.9

1.1

1.5

1.3

1.8

3

> 2

< 0.1

0.625

Ø 0.1

Ø 0.08

UNIT

[T]

[K]

[mA]

[mA]

[%]

[%]

[%]

[K⁻¹]

[K⁻¹]

[μV]

[Ω]

[Ω]

[Ω]

[Ω]

 $[\Omega]$

[Ω]

[T]

[%]

[mm²]

[mm]

[mm]

[μV/K]

[mV/T]

Vertical Hall sensors

From Schurrig [15] Genesis of a vertical Hall sensor (Popovic,1984)



Three-axis Hall magnetic devices





Three axis sensors

- Magnitude and direction of \mathbf{B}
- •Magnetic field maps
- •Field not homogeneous
- •Two or three components in a small volume
- Ex: Phase measurement in a undulator



Conventional solution...

Inconveniences:

- •Spatial resolution limited by the distance of single elements
- •Orthogonality of the sensitivity axes
- •Flux density for the three axis is not measured in the same spot



Three sensors glued in a glass cube

From R. Ruber, "Magnets for accelerator applications", (2008)





Measure the 3 components of B but... Cross sensitivity between axes to be removed



From non plate like sensors to 3D sensors

2 vertical hall sensors



Measure Bx, By (2D)

Tri-axial chip on a single crystal by merging : -vertical device+ horizontal non plate one

um

-Four bias current contacts in the corner of a silicon block

CS-0791

HUH 300

-Four sense contacts in the middle

Chip layout

The Square Hall sensor (C.Schott, 1999)





pads

IC Hall sensors: the architecture

≻Multi-axes Hall sensor+ Integrated circuitry

•Increase current and amplify the voltage,

•offset & planar effect reduction (spinning current technique, pairing)

Planar + vertical elements S=5V/T



Depletion Layer -Substrate (b

Complementary Metal Oxide Technology

(oxide growth, ion implantation, deposition, etching, epitaxy) + N well

Depletion Layer: Isolation







•Offset, 1/f noise, planar effect cancellation, •current supply





3 D Hall magnetometers with IC: an example

Multi-axes Hall sensor
 + Integrated circuitry :
 Integrated hall sensors



External electronic:

•5 V power supply supplied by USB,
•a circuit board (14x55 mm²) to digitize (16 bits), compensate temperature variation and gain offset

➢Firmware (standard compatible with USB protocols)

Software in Labview (USB driver included)

Sensor IC: 16x4x2 mm³





P. Keller, Metrolab Instruments, Switzerland, "A new generation of Hall Magnetometers" Magnetics Conference 2008





Offset reduction by orthogonal coupling

Principle : Mutual compensation of asymmetries.

When the current is turned off by 90° -Offset inverted

 $-V_{\rm H}$ remains the same.

Devices electrically connected in parallel with orthogonal current directions

Coupling of 2 sensors





•Systematic offset components are cancelled out.

- •Time varying offsets are also compensated.
- Offset can be reduced by one or two orders of magnitude.

Not sufficient if the Hall devices matching is not sable in time. Draw back : Increase the chip size and the biasing current.





Offset reduction by "Spinning current technique"

•Goal : Minimize V_{off} (also the 1/f noise and the V_{planar} contribution)

•Sensor element : Symmetrical (cross-shape) geometry

Principle (based on orthogonal sensor pairing)
➤ Terminals of the Hall device are periodically commutated and alternatively used as the current (input) and the sense (output) contacts
➢ If the biasing state of a Hall plate is turned by 90° than its offset changes its sign while the Hall voltage remains unchanged.

•Conditions of filtering : spinning frequency is significantly higher than the highest frequency of the measured magnetic field and of the corner frequency of the 1/f noise

•Result : V_{off} appears as AC voltage and V_{H} like a DC one, AC part can be filtered.

Residual offset equivalent to 10-100 μT

NB : *Time-varying offset e.g. due to temperature and stress remains a problem associated with orthogonal coupling.*









Also the planar effect is reduced..





Reduction of the planar voltage V_{PH}

- Bridge model (example of a horizontal device)Hall planar effect and magneto resistance have the same physical origin.
- •Increase of the resistance for the velocity carrier component perpendicular to the magnetic field.
- •Apparition of a ΔR for direction perpendicular to B
- $\bullet V_{\text{PH}}$ treated like the offset in voltage

Without a spinning current, the ratio

$$V_{\rm P} / V_{\rm H} = 1.3\%;$$

With a spinning current, $V_P / V_H = 0.02\%$.

D.R Popovic et al., IEEE TRANS. ON INSTRU. MEAS, VOL. 56, NO. 4, 2007

Three axis Teslameter specifications

Example of the SENIS 3-Axis Teslameter

- Full scale (nominal)
- Output voltages
- Sensitivity to d.c. magnetic field
- Tolerances of sensitivity (B = 1T d.c)
- Temp. coefficient of sensitivity
- Non-linearity of output (B <= 2T)
- Planar Hall effect: Vplan / Vvert (B = 1T)
- Long-term instability of sensitivity
- Offset (B = 0T)
- Temp. coefficient of offset

D.R Popovic et al., IMMW14, 2005

Standard accuracy ~ 0.1 %

Can be improved up to 0.01% only with an appropriate (and careful) calibration

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28 Stéphane Sanfilippo, "Hall Devices", CAS Magnets, 16-25 June 2009

differential 5 V/T (0.5mV/G) < ± 0.1 % < 100 ppm /°C < 0.05 % < 0.01% < 1 % over 10 years < ± 1 mV (0.2mT) < (0.02mT/°C)

± 2 T

3D Hall Magnetometers : Challenges

Status

- •Total field component (Bx,By,Bz),
- •Strength: Field up to 20 T
- •Hall planar, offset, temperature effects compensated
- •Routinely 1% of accuracy, 0.01% reachable with proper (and careful) calibration.
- •Mapping : Point like-active volume and 2000 samples (Bx, By, Bz)/sec
- •Compact, flexible, easy to handle
- •Standard USB interface
- •Simple to program and customize

Challenges

•Improve accuracy (routinely to 0.05%?)

- Sensors architecture : Improve the orthogonality of the sensors
- ➤3D Calibration (simplified method, small calibrator)
- ➢Noise reduction (1/f low frequency)
- Drift of the offset in time
- Encapsulation process to improve (reduce packaging stress)
- •**Cryogenic application with IC sensors** (freezing, quantum Hall effect), a redesign of the sensor is needed
- •**Miniaturization** (magnet with sub millimeter gap)
- •Performance/price ratio

Overview of a 3D calibration method

Old method : only **main axes calibration** of the sensor

New method : 3D Full scan

Principle of the method :

•Rotate sensor over two orthogonal axes in constant homogeneous field , θ and ϕ should be measured very precisely [0.02 mrad] by 3 small coils. |B| from NMR coils

•Decompose the Hall-voltage in orthogonal functions: spherical harmonics for θ and ϕ , Chebyshev polynomials for |B|.

 $= B_x, B_y, B_z$

•Repeat for several field strengths and temperatures.

•Find the coefficients c_{klm} , d_{nlm}

k

n

1

$$Y(|B|, t, \theta, \varphi) = \sum \sum \sum \sum_{l=1}^{l} c_{klm} T_k(B) d_{nlm} T_n(t) Y_{lm}(\theta, \varphi)$$

m=0

Solve inverse problem :

Vhall₁, Vhall₂, Vhall₃, T

c_{klm}, d_{nlm}

Measurement of 3 x V hall and T at θ , $\phi = n x 22.5$ degree

φ

Y00 = offset

θ

Y10 = $\cos \Theta$ Y11 = 0 by rotation Y20 = non-linearity Y21 Y22 = planar Hall effect Y30 = non-linearity Y31 Y32 = 3D? Hall effect Y33

Y40 = non-linearity

F. Bergsma "Calibration of hall sensors in three dimensions", presented at 13th IMMW 2003, Stanford, California [17]

F. Bergsma, "Progress on the 3D calibration of hall probes", presented at 14th IMMW, Geneva, Switzerland (2005) [17]

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3D Magnetic sensor calibrator

Calibrator (Patent 7259550)

Scale in Gauss

Plotted in figure: $|Bold-Bnew|(\theta,\phi)$ Color scale = |Bold|-|Bnew| Blue = -31 Gauss. Red=0 No error along the axes, $2^{\circ}/_{\circ\circ}$ off axes

Not very easy!: "Mass" production => simplify hardware and software!

Hall probes as field measurement technique

Questions to answer:

- •Measurements: Field component, total (Bx,By,Bz), field integral to measure ?
- •**Field characteristics**: Strength, uniformity, AC/DC?
- •Accuracy needed: % or 10 ppm?
- •Access: What access do you have to the region measured? Precision and reproducibility of the positioning?
- •Environment: cryogenic, room temperature?
- •Constraints: Time schedule, cost, human resources..

Accuracy Medium: 10^{-4} to 10^{-2} of the reading range Field range : mT...20-30 T

Hall probes as field measurement technique (2)

Pro

- •Easy to use, easily portable/moved
- •Inexpensive, big market
- •Can be inserted in narrow apertures (undulators)
- •Variable sensitivity (as function of I_{bias})
- •Easy element to integrate in a electronic circuit
- •Fast measurement (instantaneous response)
- •Medium accuracy for single component measurement (~0.01%)., resolution ~0.5 G.
- •Covers a very broad range of B
- •Can be used for time varying magnetic field
- •Works in non-uniform field
- Can be used for low temperature measurementsField mapper (measure the three components)

Cons

- •Temperature sensitivity
- •Non linearity V=f(B)
- •Offset to be compensated
- •Drift of offset, NL and temperature sensitivity with time
- •Lower accuracy for integrated circuit sensor: below % is difficult to achieve
- •Cross talk between axes (Planar hall effect)
- •Noise coming from the circuitry
- •Calibration (delicate for multi axes sensors)

Field measurement and Mapping in conventional magnets

Magnetic measurements of resistive magnets at the Paul Scherrer Institute

Harmonic measurements

Sextupole measurements in the 15 m long LHC dipoles during injection phase.

Field measurements in Insertion Devices Undulator measurements at the Paul Scherrer Institute.

Hall probe measurements at the Paul Scherrer Institute

Hall Probe Semicond. material I max U _{Hall} Longitudinal range Horizontal range Vertical range Long./Transv./Vert. Resolution Maximum calibrated Field Hall Probe absolute accuracy Hall probe resolution	$\begin{array}{c} \text{Siemens SVB 601S1} \\ \text{InAs} \\ 400 \text{ mA} \\ 60 \text{ mV}@1\text{T} \\ 2100 \text{ mm} \\ 650 \text{ mm} \\ 360 \text{ mm} \\ 10 \text{ mm} \\ 3.1 \text{ T} \\ 100 \text{ ppm} \\ 1 \mu\text{T} \end{array}$	Carriage
Temperature sensibility Measurement procedure Leveling of the magnet	70 ppm/°C	

- Probe position measurement w.r.t magnet coordinates
- Longitudinal variation on the probe (step of 2 mm, 20 ms time) (line integral)
- DAQ of voltage (HP/Agilent 3458A digital multimeter)
- Proceed with next line or next current
- Post processing of the data
 - Local field, field integral, magnetic length
 - ✓ Field quality
 - \checkmark 2D/3D field maps (volume in scanning five vertical planes)

anite block

ABSENTE DE DECE

Digital multimeters (2)

and the owned

6,8

 19.8 ± 0.1

Program interface

Air pad

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36,

Hall probe measurements at the Paul Scherrer Institute (2)

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C. Mark S

b3/b5 snap back measurements in LHC cryo-dipoles

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b_3/b_5 harmonic hall probe

Field measurements of the insertion devices (ID)

Insertion Device: Periodic array of magnetic poles providing a sinusoidal magnetic field on axis with high peak intensity and a shortest period. Goal: High intensity source of synchrotron radiation

Undulator parameter

$$K = 0.0934 \cdot B[T] \cdot \lambda_u[mm]$$

Constructive interference of radiation emitted at different poles

Technology used for Undulator and wigglers :

•Permanent Magnets (NdFeB, Br=1.2-1.4T) or Sm₂Co₁₇ (Br=1.05T)

•Electromagnet technology for long period undulators

•Superconducting technology for field higher than 2 T

Magnetic field specifications

To minimise the perturbation to the stored beam:

Integral of field over length of IDExit position and angle of electron beam

To maximize the spectral properties: Magnetic field at each point to know the path of electron. Keep the **phase error** low (1..2 degrees) (**incomplete constructive interference, reduces the Angular flux**)

Origins of the phase error:

- •Peak Field fluctuations
- •Period fluctuations
- •Field Shape fluctuations

From Elleaume [21]

Measured with a stretched wire!

c) Phase error

$$\int \infty \frac{\pi}{(1+K^{2}/2)} (1+\frac{2\gamma^{2}}{\lambda_{0}} \int_{\lambda_{0}/2} (\int_{-\infty}^{z} B_{y}(z).dz)^{2} dz$$

Electric field produced by one electron

Local field measurement vs longitudinal coordinate using on-the-fly scanning Hall probes

Undulator measurements at the Paul Scherrer Institute (1)

Hall sensors:

- •3 X 1-dim Siemens Hall sensors mounted on a print board
- •Range: up to 1.8 T
- •accuracy: 0.01%
- •Non linearity: <0.05 %
- •Output noise @ 20 ms integration time <0.06 G
- •Input current :5 mA

J.Chavanne, C Penel,

(ESRF Insertion Device Field Measurement Benches)

Hall probe bench (ESRF design) :

•4 m granite support (350 x 600 mm², width, eight), flatness 15 μ m

- •Anorad linear motor mounted on the granite
- •Heidenhain linear encoder
- •longitudinal movement (3.5 m, 0.1 µm resolution)

•Accuracy of the sensor position $<20 \ \mu m$ (after software correction based on laser calibration)

Hall probe keeper

Courtesy of T. Schmidt

Undulator measurements at the Paul Scherrer Institute (2)

•Hall measurements based on a calibrated 3x D Hall sensor from SIEMENS and SENIS

•On-the Fly scanning is essential to reduce the sensor vibration (precision) and reduce the

- measuring time. Speed up 30mm/s, 2000-5000 points per components
- •Typical scan : L=2500 mm, 1pt/mm/comp, speed=20 mm/sec. Time for a scan : 2min
- •Correction of the file integral using stretched wire measurements
- •Hall planar effect avoided by measuring only one polarization at the time
- •What is observed : Field integral, trajectory, phase error

Typical hall data processing:

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□Hall probes are among the most commonly used sensors for magnetic field measurement and field mapping:

Summary

- Hall voltages are measureable quantities
- Simple, linear, inexpensive, available in arrays
- Sensors can be integrated within devices.

Errors involved in measurement are mostly due to temperature, planar effects and offsets.

Three dimensional Hall sensors are constantly improving :

- ✓Offset, noise and planar hall effect are minimized but...
- ✓ Sensitivity has to be increased up to 0.01-0.05% (routine measurement)

Simplified calibration procedure to be found and practical calibrator to be designed.

□ We invite you to join this challenging field. There are still many opportunities to invent new designs and develop techniques to measure magnetic field. So please **join us**

•Vjeran Vrankovic, Paul Scherrer Institute, Magnet section
•Thomas Schmidt, Paul Scherrer Institute, Insertion Device
•Elena Mashkina, Forschungszentrum Karlsruhe GmbH
•Philip Keller Metrolab Instrument Geneva
•Dragana and Radivoje Popovic, SENIS GmbH Zürich

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Any questions?

Announcement

16th International Magnetic Measurement Workshop IMMW16

Paul Scherrer Institut

16th International Magnetic Measurement Workshop IMMW16

Scope •Magnetic field measurements on accelerator magnets and insertion devices •Field measurement techniques •Field measurement devices •Stimulate world wide exchange and cooperation.

> 26-29 October 2009 Park-Hotel Bad Zurzach, Switzerland

http://immw16.web.psi.ch/

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Additional slides

Terminology

Hall plate or hall element : Semiconductor element (slice or film) sensitive to magnetic field.

Hall generator or Hall sensor : Hall element +electrodes glued on a substrate. Biased with a current, it converts as an active sensor the magnetic field (stimulus) in a electrical signal.

Hall probe : Hall generator mounted in a holder. Mostly used to measure magnetic fields and perform field mapping on magnets.

Integrated Circuit (IC) Hall sensor : Hall sensor with associated electronic integrated in the same chip to bias the sensor, amplify the output signals and compensate the parasitic effects.

Accuracy: Degree of correctness of a measured value compared to the true value. It may be represented in percent of the input full scale.

Resolution : The smallest distinguishable increment that the system can discriminate.

Repeatability error : The inability of the instrument to produce the same value among a number of consecutive measurements under identical conditions.

Transfer function : output (voltage)/ stimulus (magnetic field) relationship. In a linear relationship the slope of the function is called sensitivity.

The integer quantum Hall effect

In low temperature and strong magnetic field

$$R_{H} = \frac{R_{K}}{n}$$
, $n = 1, 2, 3, \cdots$ $R_{K} = \frac{h}{e^{2}}$

effect as much as 1 % on calibration coefficient

K.von Klitzing, G.Dorda, M.Pepper, Phys.Rev.Lett, Vol.45, 494-1402, 1980

Applications of the Hall sensors

- •Hall effect sensors can be applied in many types of sensing devices.
- •Quantity (parameter) to be sensed has to incorporate a magnetic field.
- •The Hall sensor senses the field produced by the magnetic system.
- •The magnetic system responds to the physical quantity to be sensed (temperature, pressure, position, etc.) through the input interface.
- •The output interface converts the electrical signal from the Hall sensor to a signal that meets the requirements of the application.

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General sensor based

on the Hall effect

Applications of the Hall sensors (2)

- Automotive Applications
- sensor ignition
- timing engine speed
- drive-by-wire
- brake-by-wire
- throttle position sensor
- current measurement

- Industrial Applications
- commutation of brushless DC motors
- cooling fans
- RPM measurement
- wheel speed sensors
- angle sensor
- current measurement
- position measurement
- distance measurement

Hall sensors : 80% of the market (2003)

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